

ABSTRACT OF THE DISCLOSURE

A reliable new IC package structure comprises an IC package having a plurality of grounding conductor plates provided around its surrounding, a first conductor plate for covering over the IC package has downwardly flexed edges at its both sides to form two lugs, and each grounding plate is upwardly cambered to wrap corresponding first conductor plates. A second conductor plate with similar shape to the first one for covering the former closely coupled first and grounding conductor plates, the both sides of the second conductor is also downwardly flexed to form two lugs. A press block having an inner cavity to shade the IC package, first and second conductor plates. Several elastic press bars are installed in said inner cavity and above grounding conductors. The press block, the second and the first conductor plates are engaged with screw to finish the assembly of the IC package of the best grounding effect, heat dissipation performance and quality associated with the additional merits of easy productivity and replaceability.

(Fig.3)